PNP Silicon General Purpose Amplifier Transistor

This PNP transistor is designed for general purpose amplifier applications. This device is housed in the SOT-723 package which is designed for low power surface mount applications, where board space is at a premium.

Features

- Reduces Board Space
- High h_{FE}, 210-460 (Typical)
- Low V_{CE(sat)}, < 0.5 V
- ESD Performance: Human Body Model; > 2000 V,

Machine Model; > 200 V

- Available in 4 mm, 8000 Unit Tape & Reel
- This is a Pb-Free Device

MAXIMUM RATINGS $(T_A = 25^{\circ}C)$

Rating	Symbol	Value	Unit
Collector-Base Voltage	V _{(BR)CBO}	-60	Vdc
Collector-Emitter Voltage	V _{(BR)CEO}	-50	Vdc
Emitter-Base Voltage	V _{(BR)EBO}	-6.0	Vdc
Collector Current - Continuous	Ic	-100	mAdc

THERMAL CHARACTERISTICS

Rating	Symbol	Max	Unit
Power Dissipation (Note 1)	P_{D}	265	mW
Junction Temperature	T_J	150	°C
Storage Temperature Range	T _{stg}	−55 ~ +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

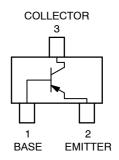
 Device mounted on a FR-4 glass epoxy printed circuit board using the minimum recommended footprint.



ON Semiconductor®

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PNP GENERAL PURPOSE AMPLIFIER TRANSISTORS SURFACE MOUNT



MARKING DIAGRAM



SOT-723 CASE 631AA



F9 = Specific Device Code M = Date Code

ORDERING INFORMATION

Device	Package	Shipping [†]
2SA2029M3T5G	SOT-723 (Pb-Free)	8000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS $(T_A = 25^{\circ}C)$

Characteristic	Symbol	Min	Тур	Max	Unit
Collector-Base Breakdown Voltage ($I_C = -50 \mu Adc, I_E = 0$)	V _{(BR)CBO}	-60	-	-	Vdc
Collector–Emitter Breakdown Voltage (I _C = -1.0 mAdc, I _B = 0)	V _{(BR)CEO}	-50	-	-	Vdc
Emitter-Base Breakdown Voltage ($I_E = -50 \mu Adc$, $I_E = 0$)	V _{(BR)EBO}	-6.0	-	-	Vdc
Collector-Base Cutoff Current (V _{CB} = -30 Vdc, I _E = 0)	I _{CBO}	-	-	-0.5	nA
Emitter-Base Cutoff Current (V _{EB} = -7.0 Vdc, I _B = 0)	I _{EBO}	-	-	-0.1	μΑ
Collector–Emitter Saturation Voltage (Note 2) $(I_C = -50 \text{ mAdc}, I_B = -5.0 \text{ mAdc})$	V _{CE(sat)}	-	-	-0.5	Vdc
DC Current Gain (Note 2) (V _{CE} = -6.0 Vdc, I _C = -1.0 mAdc)	h _{FE}	120	ı	560	-
Transition Frequency ($V_{CE} = -12 \text{ Vdc}$, $I_{C} = -2.0 \text{ mAdc}$, $f = 30 \text{ MHz}$)	f _T	-	140	-	MHz
Output Capacitance (V _{CB} = -12 Vdc, I _E = 0 Adc, f = 1.0 MHz)	C _{OB}	-	3.5	-	pF

^{2.} Pulse Test: Pulse Width \leq 300 $\mu s,$ Duty Cycle \leq 2%.

TYPICAL ELECTRICAL CHARACTERISTICS

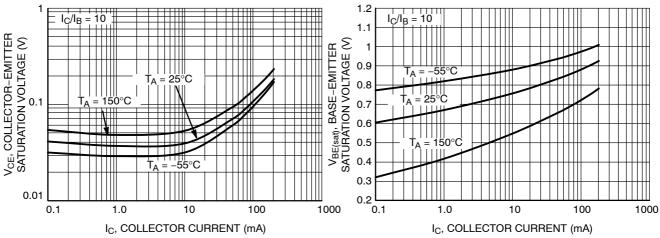


Figure 1. Collector–Emitter Saturation Voltage vs. Collector Current

Figure 2. Base-Emitter Saturation Voltage vs.
Collector Current

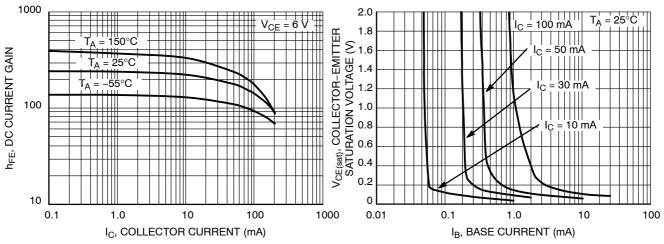


Figure 3. DC Current Gain vs. Collector Current

Figure 4. Saturation Region

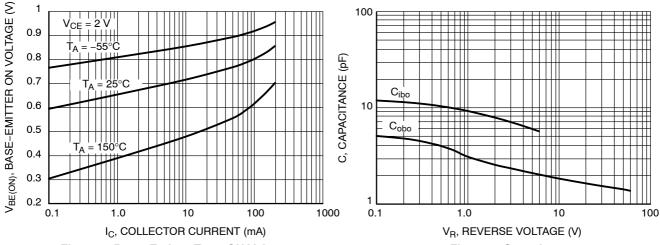


Figure 5. Base-Emitter Turn-ON Voltage vs.
Collector Current

Figure 6. Capacitance

TYPICAL ELECTRICAL CHARACTERISTICS

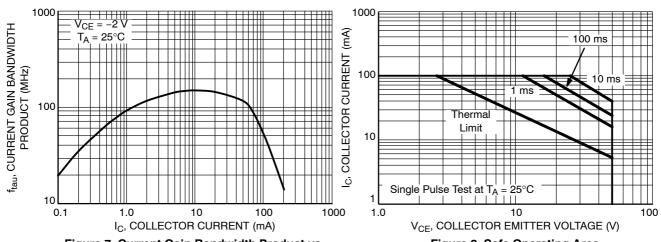
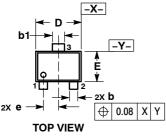


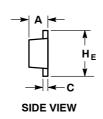
Figure 7. Current Gain Bandwidth Product vs.
Collector Current

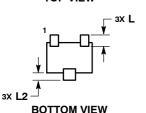
Figure 8. Safe Operating Area

PACKAGE DIMENSIONS

SOT-723 CASE 631AA ISSUE D





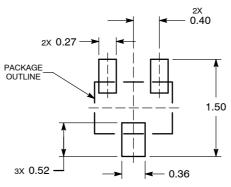


NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS.
 MAXIMUM LEAD THICKNESS INCLUDES LEAD
 FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL
- DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS

	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	0.45	0.50	0.55	
b	0.15	0.21	0.27	
b1	0.25	0.31	0.37	
C	0.07	0.12	0.17	
D	1.15	1.20	1.25	
Е	0.75	0.80	0.85	
е	0.40 BSC			
ΗE	1.15	1.20	1.25	
L	0.29 REF			
L2	0.15	0.20	0.25	

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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